

In the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously presented) An electrostatic-capacitance-type coordinate input device comprising an input sensor formed such that an X electrode layer and a Y electrode layer for detecting electrostatic capacitance are multilayered on a flexible substrate,

wherein said input sensor is bonded on a rear surface of an insulating support plate for supporting said input sensor.

2. (Original) An electrostatic-capacitance-type coordinate input device according to Claim 1, wherein a recess to which the input sensor is fitted is formed on the rear surface of said support plate at a position where said input sensor is bonded.

3. (Previously presented) An electrostatic-capacitance-type coordinate input device according to Claim 1, wherein a pointing section for pointing a position of said input sensor is formed in said support plate.

4. (New) An coordinate input device, comprising:

an input sensor having an electrode for detecting electrostatic capacitance, the electrode being formed on a flexible substrate;
a housing having an upper surface, the upper surface having obverse and reverse sides, the obverse side being exposed;

wherein the input sensor is disposed on the reverse side of the upper surface.

5. (New) The device according to claim 4, wherein a recessed area is provided on the reverse side of the housing and the input sensor is bonded to the recessed area.

6. (New) The device according to claim 4, wherein an indication portion is formed on the obverse side of the upper surface, and disposed to indicate the position of the input sensor.

7. (New) The device according to claim 4, wherein the input sensor is formed as a film substrate and the film substrate is bonded to an arcuate section formed in the upper surface.

8. (New) A device, comprising;

an input device having a coordinate-input sensor formed on a flexible substrate and having an electrode layer for detecting electrostatic capacitance;

a device housing having an insulating portion having obverse and reverse sides, the obverse side being exposed;

wherein the input sensor is disposed on the reverse side of the insulating portion and an input operation is performable at the obverse side.

9. (New) The device according to claim 8, wherein the input sensor is bonded to an arcuate section formed in the insulating portion.

10. (New) The device according to claim 8, wherein the input sensor is bonded to a recessed area formed in the reverse side.